LINEAR TECHNOLOGY MATERIALS DECLARATION

LT3008MPTS8-1.5#TRPBF **(Engineering Calculation)** TSOT-23

TOTAL MASS (g): **0.01240669**

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COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.000429**	**1000000**	**34578.12**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004582	975000	369316.9
		Iron (Fe)	7439-89-6	0.000113	24000	9107.989
		Phosporus (P)	7723-14-0	1E-06	300	80.60168
		Zinc (Zn)	7440-66-6	3E-06	700	241.805
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		**0.004699**	**1000000**	**378747.3**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.00066269	1000000	53413.92
		External Plating Total:		**0.00066269**	**1000000**	**53413.92**
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	8E-05	1000000	6448.134
		Internal Plating Total:		**8E-05**	**1000000**	**6448.134**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000351	750000	28291.19
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0.000117	250000	9430.396
		Die Attach Total:		**0.000468**	**1000000**	**37721.59**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000777	130000	62627.5
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.004963	830000	400026.1
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0.000209	35000	16845.75
		Carbon Black (C)	1333-86-4	3E-05	5000	2418.05
		Encapsulation Total:		**0.005979**	**1000000**	**481917.4**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**8.9E-05**	**1000000**	**7173.549**